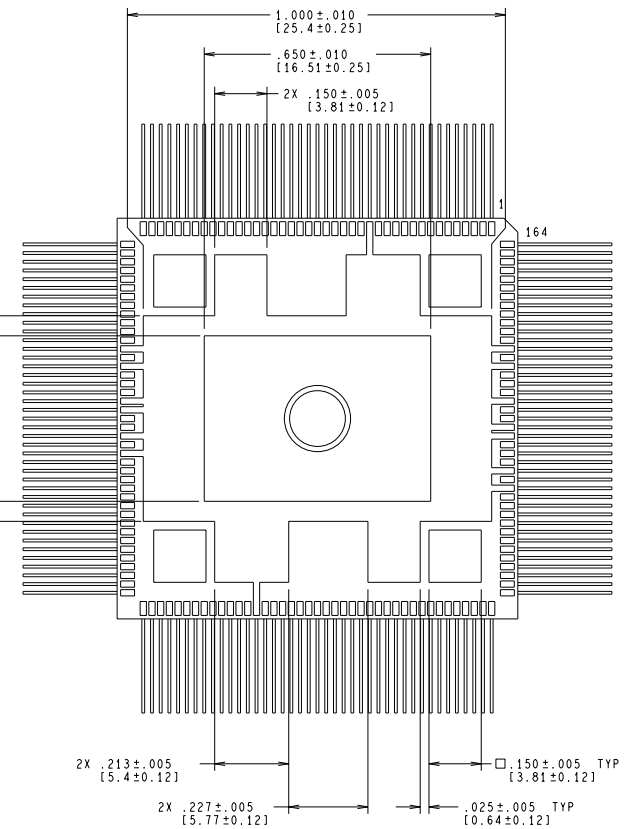
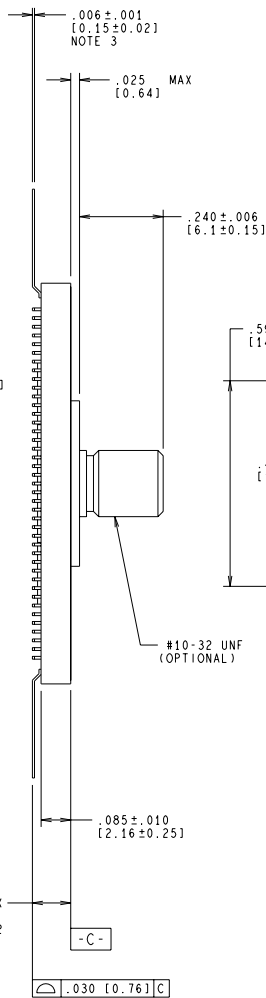
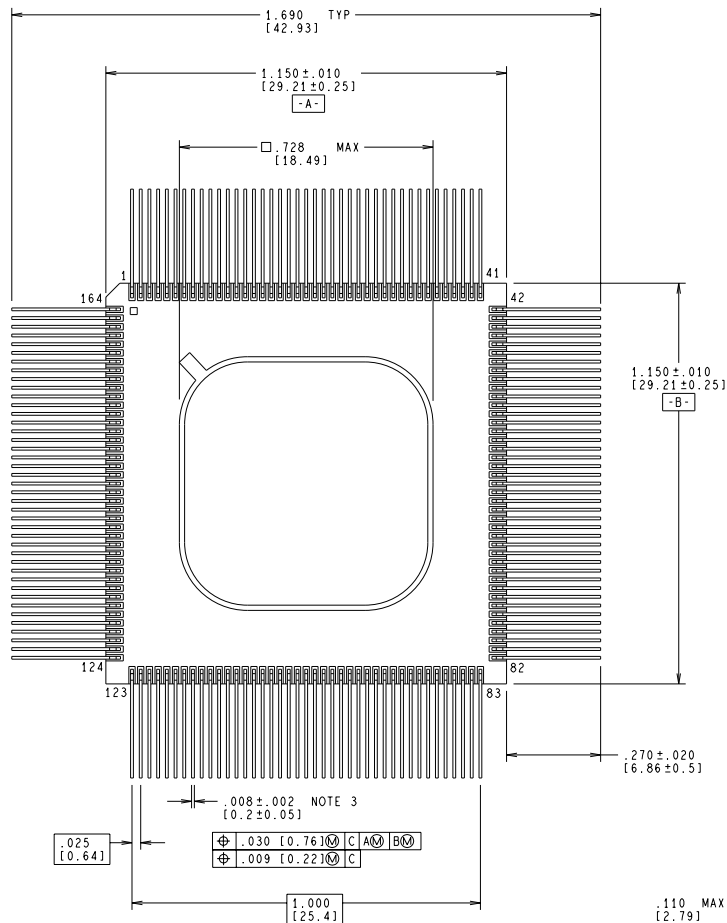


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REVISE AND REDRAW PER ECN.	10383	09/29/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

1. ALL EXPOSED METAL AND METALIZED AREA SHALL BE GOLD PLATED 50-225 MICROINCHES[1.3-5.7 MICROMETERS MINIMUM THICK OVER 50-350 MICROINCHES[1.3-8.9 MICROMETERS] NICKEL PLATE.
2. MAXIMUM DIMENSION APPLIED TO TOP OF LID OR LEADFRAME, WHICHEVER IS GREATER DISTANCE FROM DATUM -C-.
3. LEAD THICKNESS AND WIDTH APPLY TO BASE METAL.
4. NO JEDEC REGISTRATION AS OF 06/93

MIL/AERO
CONFIGURATION CONTROL

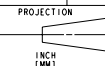
MIL-M-38510
CONFIGURATION CONTROL

APPROVALS		DATE				
DRAWN	D. F. Grady	09/28/94				
DFTG. CHK.						
ENGR. CHK.						
APPROVAL						
			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	C	MKT-EL164A	B
			DO NOT SCALE DRAWING			
			SHEET 1 of 1			



National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

CERAMIC QUAD FLATPACK,
164 LEAD



SCALE
N/A

SIZE
C

DRAWING NUMBER
MKT-EL164A

REV
B

DO NOT SCALE DRAWING

SHEET 1 of 1